



STPS5L25B/B-1

LOW DROP POWER SCHOTTKY RECTIFIER

MAIN PRODUCT CHARACTERISTICS

I_{F(AV)}	5 A
V_{RRM}	25 V
T_j (max)	150°C
V_F (max)	0.35 V

FEATURES AND BENEFITS

- VERY LOW FORWARD VOLTAGE DROP FOR LESS POWER DISSIPATION AND REDUCED HEATSINK
- OPTIMIZED CONDUCTION/REVERSE LOSSES TRADE-OFF WHICH MEANS THE HIGHEST EFFICIENCY IN THE APPLICATIONS
- HIGH POWER SURFACE MOUNT MINIATURE PACKAGE
- AVALANCHE RATED

DESCRIPTION

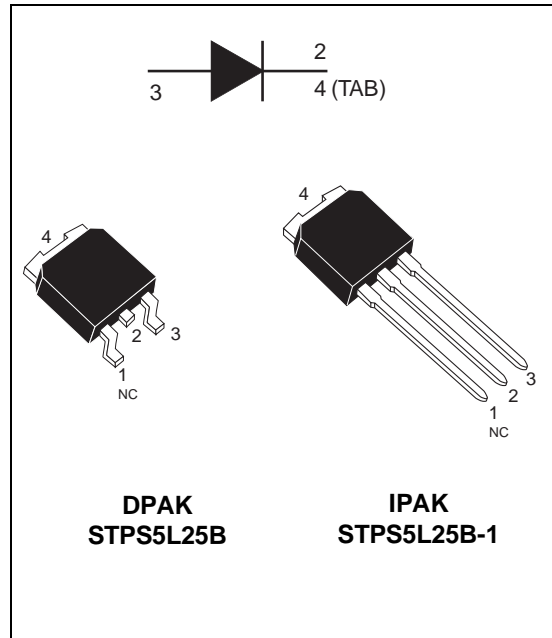
Single Schottky rectifier suited to Switched Mode Power Supplies and high frequency DC to DC converters.

This device is especially intended for use as a Rectifier at the secondary of 3.3V SMPS units.

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit	
V _{RRM}	Repetitive peak reverse voltage	25	V	
I _{F(RMS)}	RMS forward current	7	A	
I _{F(AV)}	Average forward current	T _c = 145°C δ = 0.5	5	A
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms Sinusoidal	75	A
I _{RRM}	Repetitive peak reverse current	t _p = 2 μs square F = 1kHz	1	A
I _{RSM}	Non repetitive peak reverse current	t _p = 100 μs square	2	A
T _{stg}	Storage temperature range	- 65 to + 150	°C	
T _j	Maximum operating junction temperature *	150	°C	
dV/dt	Critical rate of rise of reverse voltage	10000	V/μs	

* : $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ thermal runaway condition for a diode on its own heatsink



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THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	Junction to case	2.5	°C/W

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Tests Conditions	Tests Conditions	Min.	Typ.	Max.	Unit	
I_R^*	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$		350	μA	
		$T_j = 125^\circ\text{C}$		55	115	mA	
V_F^*	Forward voltage drop	$T_j = 25^\circ\text{C}$	$I_F = 5\text{ A}$		0.47	V	
		$T_j = 125^\circ\text{C}$		0.31	0.35		
		$T_j = 25^\circ\text{C}$		$I_F = 10\text{ A}$			0.59
		$T_j = 125^\circ\text{C}$			0.41		0.50

Pulse test : * $t_p = 380\ \mu\text{s}$, $\delta < 2\%$

To evaluate the maximum conduction losses use the following equation :

$$P = 0.2 \times I_{F(AV)} + 0.030 I_{F(RMS)}^2$$

Fig. 1: Average forward power dissipation versus average forward current.

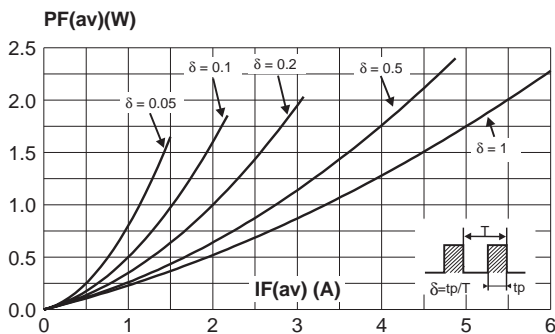


Fig. 2: Average forward current versus ambient temperature ($\delta=0.5$).

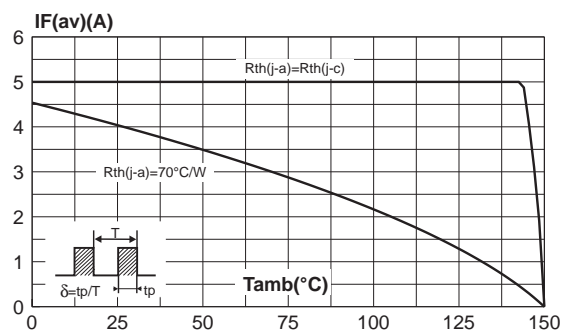


Fig. 3: Non repetitive surge peak forward current versus overload duration (maximum values).

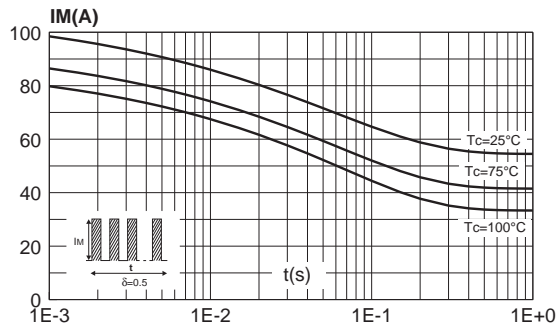


Fig. 4: Relative variation of thermal impedance junction to case versus pulse duration.

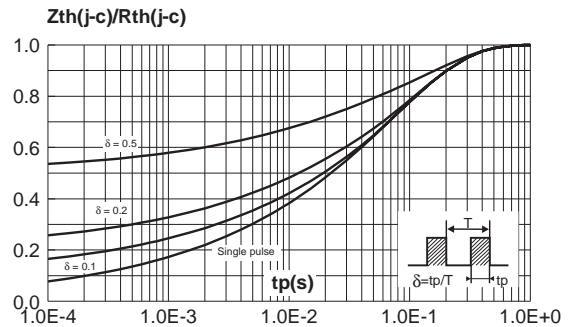


Fig. 5: Reverse leakage current versus reverse voltage applied (typical values).

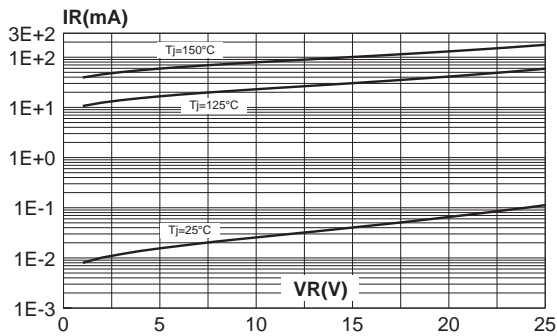


Fig. 6: Junction capacitance versus reverse voltage applied (typical values).

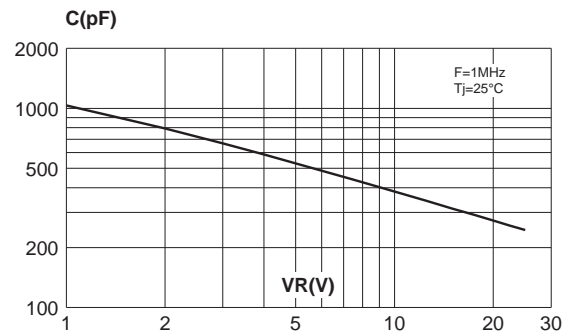


Fig. 7: Forward voltage drop versus forward current (maximum values).

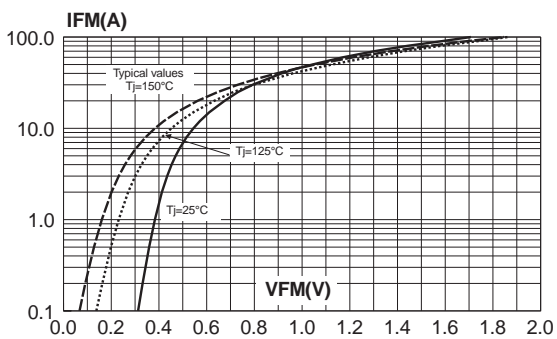
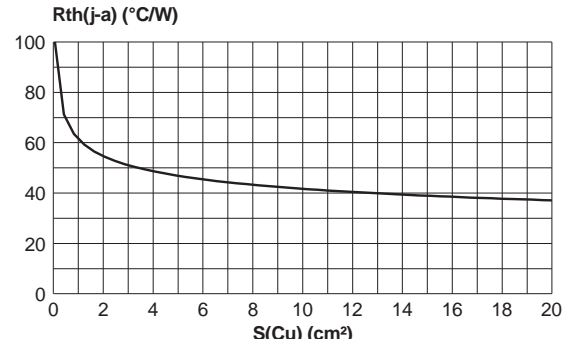
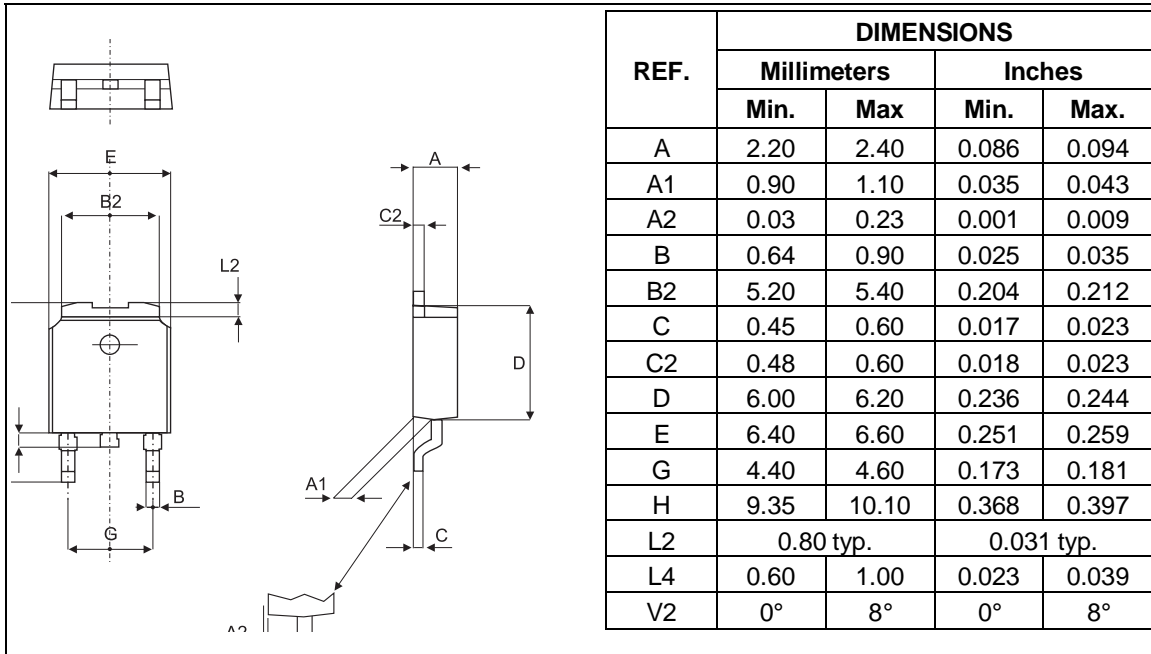


Fig. 8: Thermal resistance junction to ambient versus copper surface under tab (Epoxy printed circuit board FR4, copper thickness: 35µm).

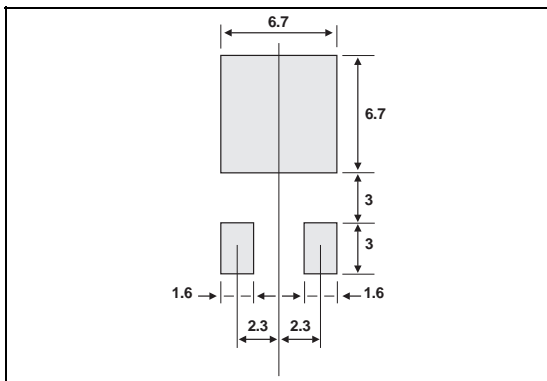


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PACKAGE MECHANICAL DATA DPAK



FOOT PRINT DIMENSIONS (in millimeters)



PACKAGE MECHANICAL DATA
IPAK

REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.2		2.4	0.086		0.094
A1	0.9		1.1	0.035		0.043
A3	0.7		1.3	0.027		0.051
B	0.64		0.9	0.025		0.035
B2	5.2		5.4	0.204		0.212
B3			0.85			0.033
B5		0.3			0.035	
B6			0.95			0.037
C	0.45		0.6	0.017		0.023
C2	0.48		0.6	0.019		0.023
D	6		6.2	0.236		0.244
E	6.4		6.6	0.252		0.260
G	4.4		4.6	0.173		0.181
H	15.9		16.3	0.626		0.641
L	9		9.4	0.354		0.370
L1	0.8		1.2	0.031		0.047
L2		0.8	1		0.031	0.039
V1		10°			10°	

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS5L25B	STPS5L25B	DPAK	0.30g	75	Tube
STPS15LB-TR	STPS5L25B	DPAK	0.30g	2500	Tape & reel
STPS5L25B-1	STPS5L25B	IPAK	0.35g	75	Tube

- Epoxy meets UL94,V0

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